

In the Specification

Immediately preceding paragraph [0001] on page 1, please insert the following heading:

--TECHNICAL FIELD--

Immediately preceding paragraph [0002] on page 1, please insert the following heading:

--BACKGROUND--

Immediately preceding paragraph [0008] on page 3, please insert the following heading:

--SUMMARY--

Immediately preceding paragraph [0022] on page 5, please insert the following heading:

--BRIEF DESCRIPTION OF THE DRAWINGS--

Please amend paragraph [0027] as follows:

--A chip 2 is die-bonded on this substrate 1 with the interposition of a tape 3 tape. The underside of the substrate 1 is provided with conductive tracks (not illustrated) which are connected, on the one hand, to solder balls 4, and, on the other hand, to the chip 2 via customary microwires (not illustrated) which run through a central channel in the substrate 1. This central channel is closed with a bonding channel closure 5 made of a molding material (potting compound) in order to protect the microwires and the active side of the chip 2. The rear side of the chip 2 (at the top in Figure 1) and the chip edges are enclosed by a molding covering 6, the molding covering 6 being connected to the surface of the substrate 1 by adhesion laterally with respect to the chip 2. The molding covering can be produced by printing or dispensing.--